

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

| | | |
|----------------------|---|--------------------------------------|
| 1.1 Company |  | STMicroelectronics International N.V |
| 1.2 PCN No. | AMS/22/13762 | |
| 1.3 Title of PCN | SOT323 5lds Transfer Qualification in Hefei TF (Assembly & Test) | |
| 1.4 Product Category | See product list | |
| 1.5 Issue date | 2022-11-14 | |

2. PCN Team

| | |
|---------------------------|----------------------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | NEMETH KRISZTINA |
| 2.1.2 Phone | +49 89460062210 |
| 2.1.3 Email | krisztina.nemeth@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Marcello SAN BIAGIO |
| 2.1.2 Marketing Manager | Salvatore DI VINCENZO |
| 2.1.3 Quality Manager | Giuseppe LISI, Jean-Marc BUGNARD |

3. Change

| | | |
|--------------|---|----------------------------|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| Transfer | Product transfer from one site to another site, even if test or process line is qualified | Hefei TF |

4. Description of change

| | | |
|--|-----------------------------------|---|
| | Old | New |
| 4.1 Description | Assembly and Test : - Carsem M | Assembly and Test : - Carsem M - Hefei TF |
| 4.2 Anticipated Impact on form, fit, function, quality, reliability or processability? | No impact | |

5. Reason / motivation for change

| | |
|----------------------|--|
| 5.1 Motivation | Additional Assembly and Test Capacity in Hefei TF. |
| 5.2 Customer Benefit | MANUFACTURING FLEXIBILITY |

6. Marking of parts / traceability of change

| | |
|-----------------|-------------------------|
| 6.1 Description | New finished good codes |
|-----------------|-------------------------|

7. Timing / schedule

| | |
|-------------------------------------|--------------|
| 7.1 Date of qualification results | 2022-11-20 |
| 7.2 Intended start of delivery | 2023-02-15 |
| 7.3 Qualification sample available? | Upon Request |

8. Qualification / Validation

| | | | |
|--|--|------------|------------|
| 8.1 Description | 13762 RER 6088-1738-W-2022_New Assembly plant TFME HEFEI for SOT 323 5 LDS.pdf | | |
| 8.2 Qualification report and qualification results | Available (see attachment) | Issue Date | 2022-11-14 |

9. Attachments (additional documentations)

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|--|
| 13762 Public product.pdf |
| 13762 RER 6088-1738-W-2022_New Assembly plant TFME HEFEI for SOT 323 5 LDS.pdf |

| 10. Affected parts | | |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| | LDK120C33R | |
| | LDK130C33R | |
| | LMV321LICT | |
| | LMV331ICT | |
| | TS881ICT | |
| | TSU101ICT | |
| | TSU111ICT | |

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